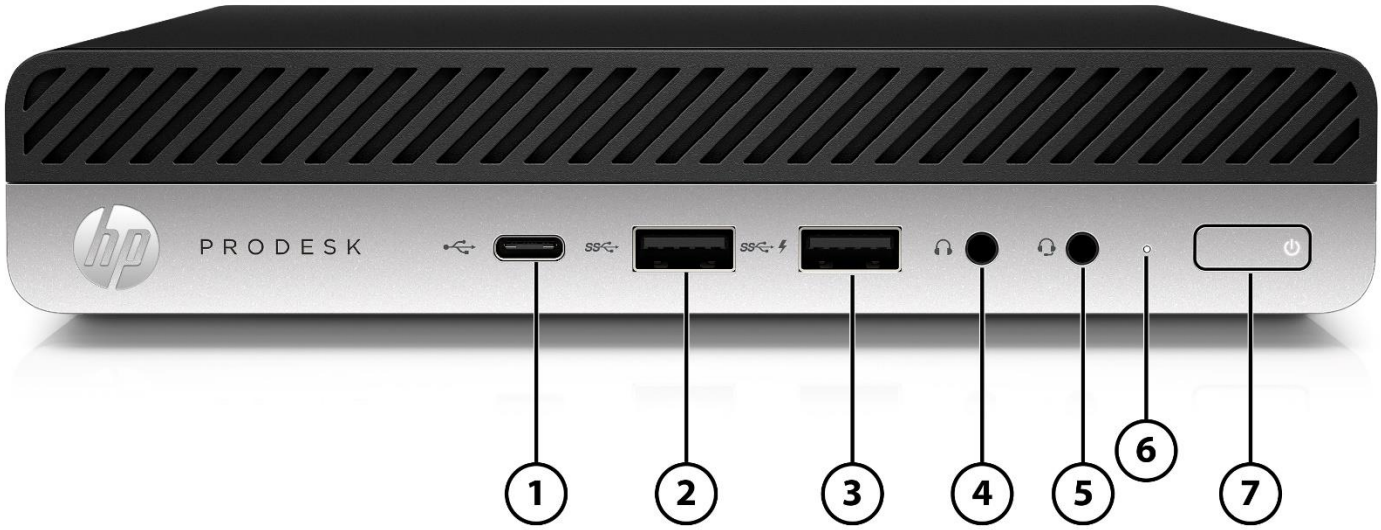
Overview

HP ProDesk 600 G4 Desktop Mini Business PC



1. USB 3.1 Gen 2 Type-C™ port
2. USB 3.1 Gen 2 port
3. USB 3.1 Gen 1
4. Headphone Jack
5. Universal Audio Jack with CTIA headset support
6. Hard drive activity light
7. Dual-state power button

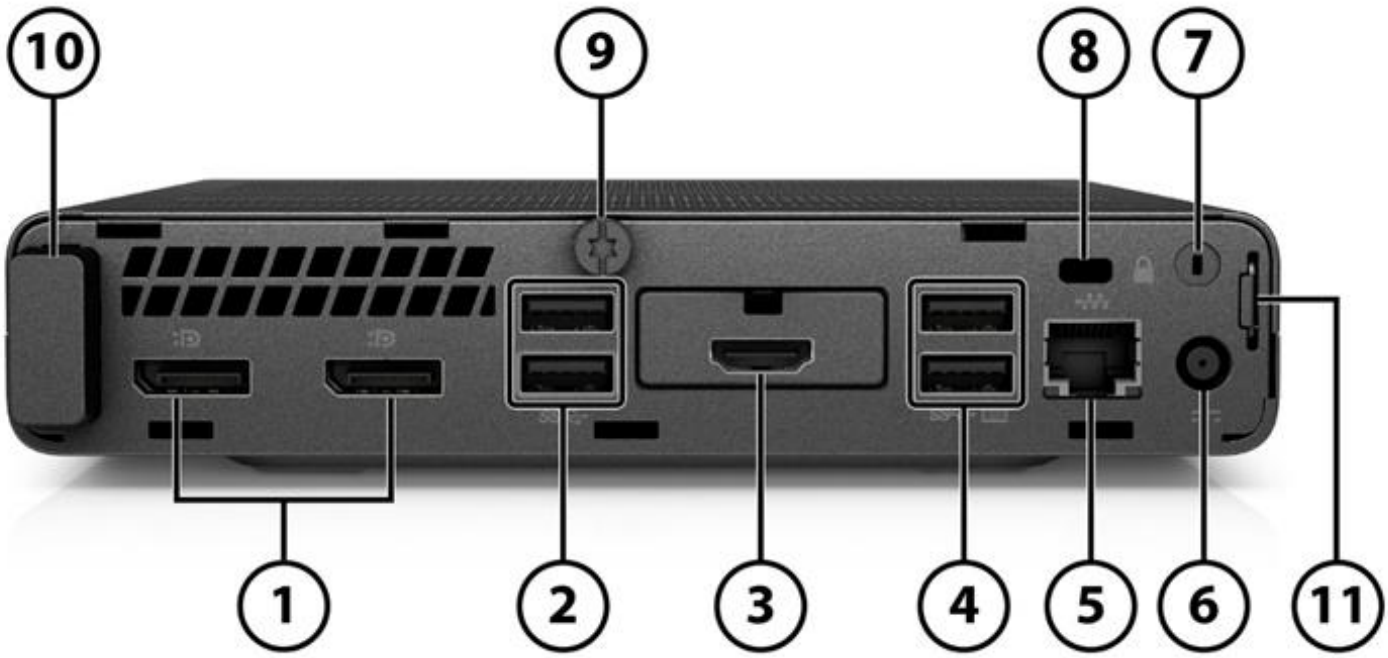
Not Shown

(3) M.2 (1 as M.2 2230 socket for WLAN/BT and 2 as M.2 2280/2230 socket for storage)

(1) 2.5" internal storage drive bay

Overview

HP ProDesk 600 G4 Desktop Mini Business PC

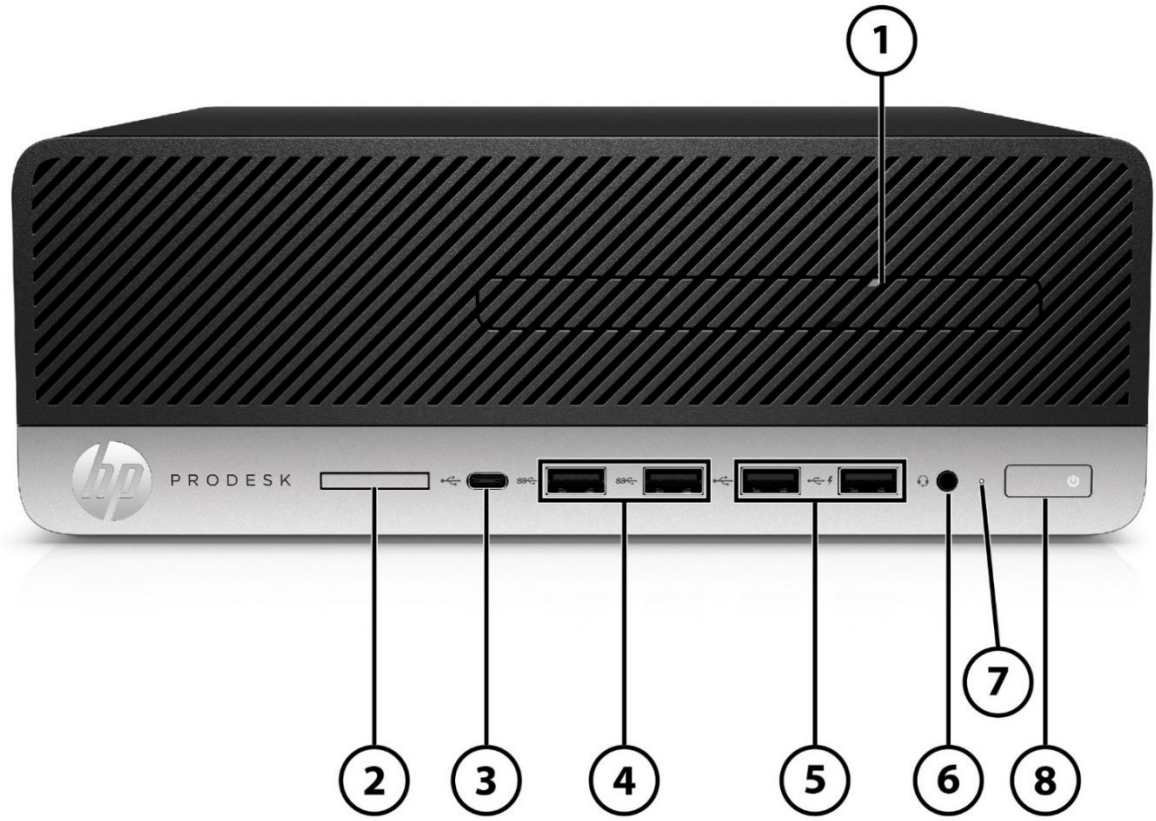


1. (2) Dual-Mode DisplayPort™ 1.2 (DP++)
2. (2) USB 3.1 Gen 2 port
3. Configurable I/O Port (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with Display Output or Serial)
4. (2) USB 3.1 Gen 1 port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
5. RJ45 network connector
6. Power connector
7. External WLAN antenna opening[1]
8. Cable lock slot
9. Cover release thumbscrew
10. Internal WLAN antenna cover
11. Padlock loop

1. Must be configured at time of purchase

Overview

HP ProDesk 600 G4 Small Form Factor Business PC



1. Slim optical drive (optional)
2. SD card 4.0 reader (optional)
3. (1) USB 3.1 Gen 2 Type-C™ port
4. (2) USB 3.1 Gen 2 port
5. (1) USB 2.0 port and (1) USB 2.0 port
6. Universal Audio Jack with CTIA headset support
7. Hard drive activity light
8. Dual-state power button

Not Shown

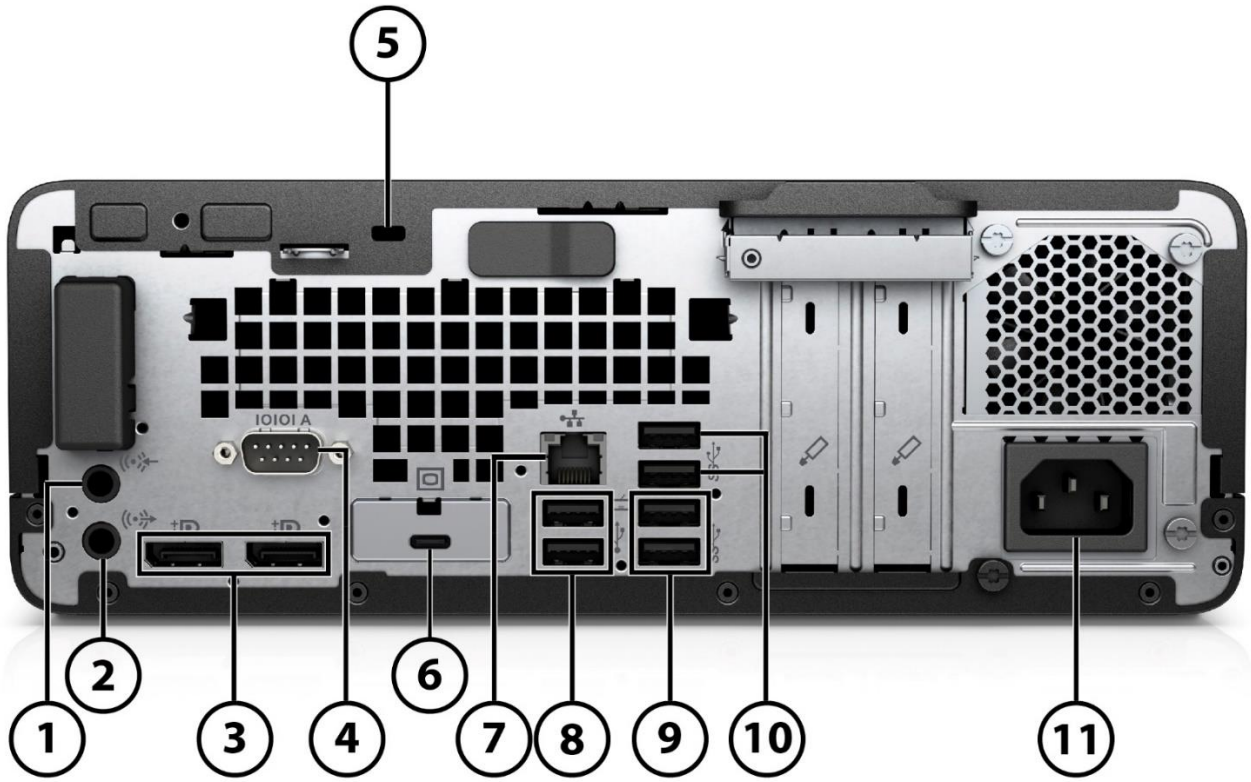
(1) PCI Express x16

(1) PCI Express x4

(2) M.2 (1 as M.2 2230 socket for WLAN/BT and 1 as M.2 2280/2230 socket for storage)

HP ProDesk 600 G4 Small Form Factor Business PC

Overview



1. Audio-in connector
2. Audio-out connector
3. (2) Dual-Mode DisplayPort™ 1.2 (DP++)
4. (1) Serial port (optional)
5. Cable lock slot

Not Shown

Port

Optional PS/2 & serial port card (connected with PCA via flyer cable)

6. (1) Configurable I/O Port (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with Display Output)
7. RJ-45 (network) jack
8. (2) USB2.0 ports supporting wakening from S4/S5 with keyboard/mouse connected)
9. (2) USB 3.1 Gen 2 port
10. (2) USB 3.1 Gen 1 port
11. Power cord connector

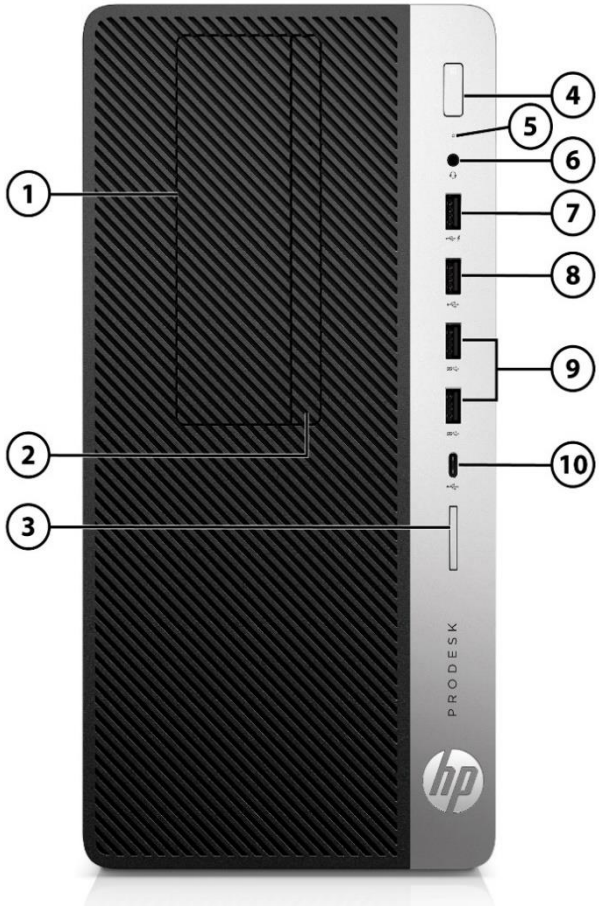
Bay

(1) 9.5mm internal optical drive bay

(1) 3.5" internal storage drive bay or (2) 2.5" internal storage drive bays

Overview

HP ProDesk 600 G4 Microtower Business PC



1. 5.25-inch drive bay (behind bezel)
2. Slim optical drive (optional)
3. SD card 4.0 reader (optional)
4. Dual-state power button
5. Hard drive activity light
6. Universal Audio Jack with CTIA headset support

Not Shown

(2) PCI Express x16 (one wired as an x4)

(2) PCI Express x1[1]

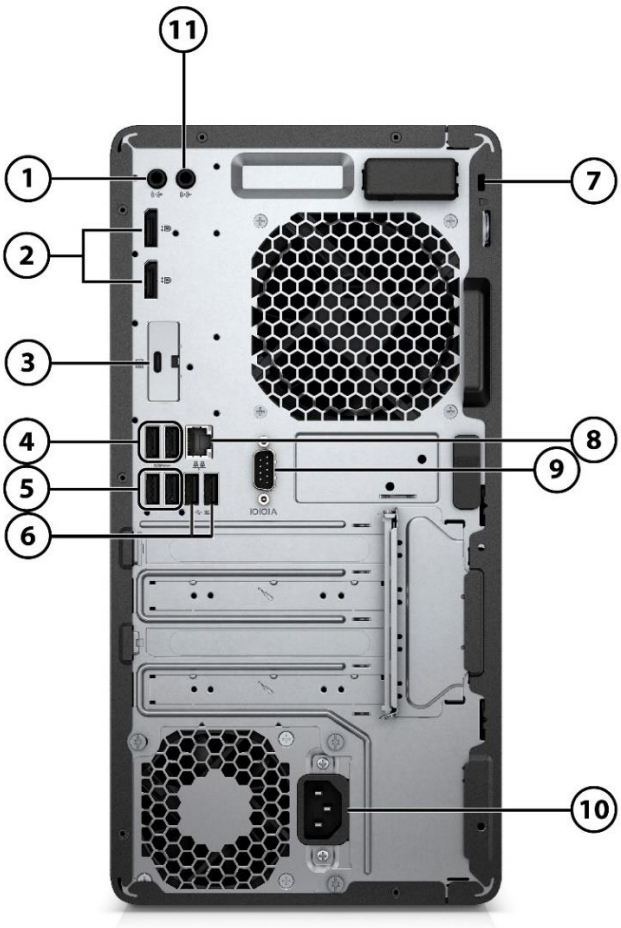
(2) M.2 (1 as M.2 2230 socket for WLAN/BT and 1 as M.2 2280/2230 socket for storage)

7. (1) USB 2.0 port
8. (1) USB 2.0 port
9. (2) USB 3.1 Gen 2 port
10. (1) USB 3.1 Gen 2 Type-C™ port

1. On certain models, it would be (1) PCI Express x1 and (1) PCI x1

Standard Features and Configurable Components (availability may vary by country)

HP ProDesk 600 G4 Microtower Business PC



1. Audio-out connector
2. (2) Dual-Mode DisplayPort™ 1.2 (DP++)
3. (1) Configurable I/O Port (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, USB Type-C™ with Display Output)
4. (2) USB2.0 ports
5. (2) USB 3.1 Gen 2 port
6. (2) USB 3.1 Gen 1 port, and supporting wakening from S4/S5 with keyboard/mouse connected)
7. Cable lock slot
8. RJ-45 (network) jack
9. (1) Serial port (optional)
10. Power cord connector

11z. Audio-in connector

Not Shown

Port

Optional PS/2 & serial port card (connected with PCA via flyer cable)

Bay

(1) 5.25” internal half-height drive bay or (2) 2.5” internal storage drive bays
(1) 3.5” internal storage drive bay

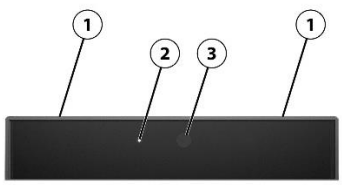
(1) 9.5mm internal optical drive bay

Standard Features and Configurable Components (availability may vary by country)

HP ProOne 600 G4 21.5" All-in-One Business PC (Touch & Non-Touch)

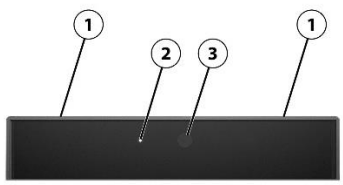
1. Pull-up webcam (optional)
2. Speakers (optional)

HD webcam (optional)



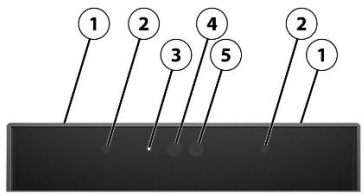
1. Dual microphones
2. Webcam light
3. HD webcam

FHD webcam (optional)



1. Dual microphones
2. Webcam light
3. FHD webcam

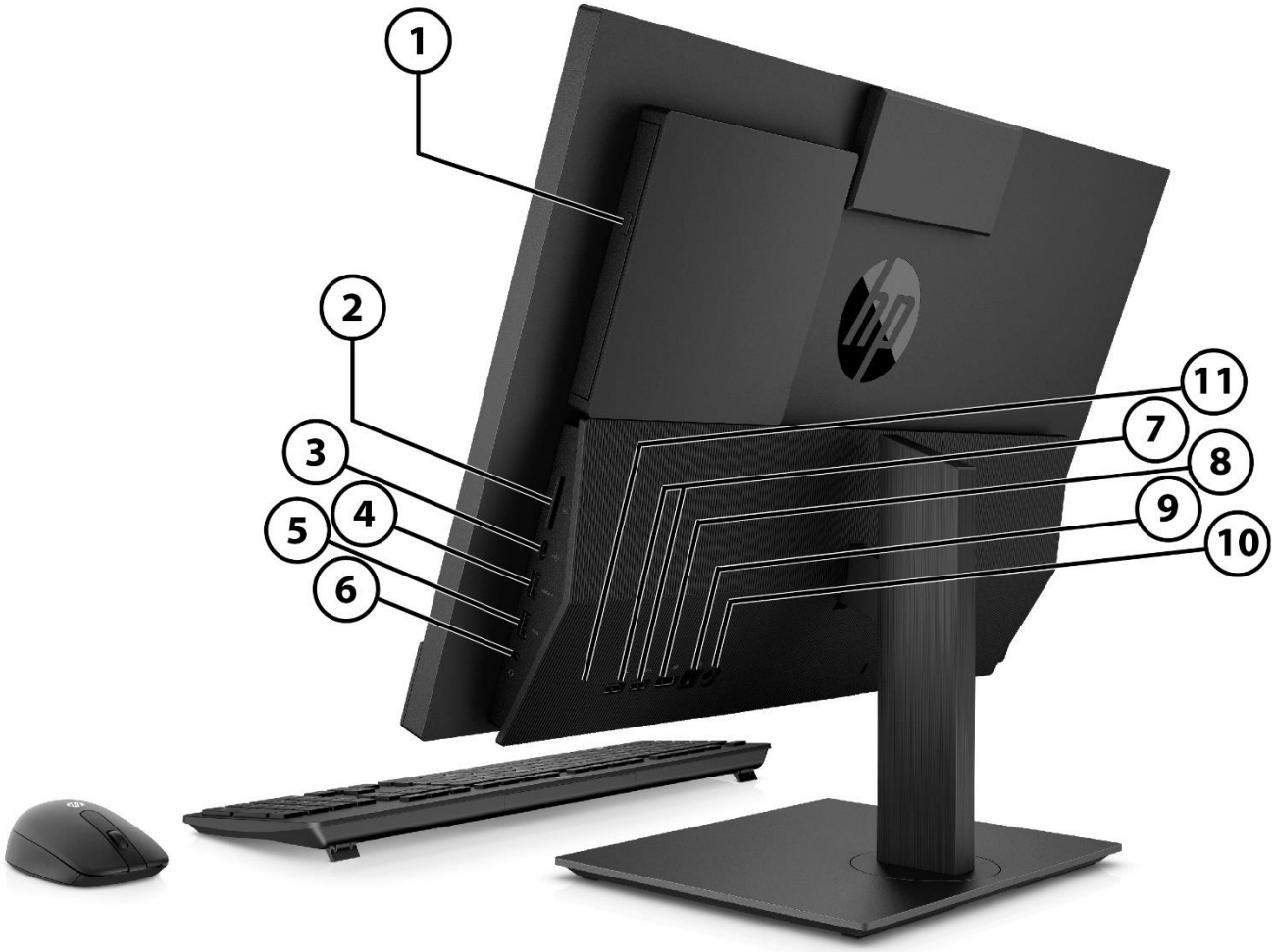
FHD webcam with Infrared (IR) sensors (optional)



1. Dual microphones
2. IR light
3. Webcam light
4. IR webcam
5. FHD webcam

Standard Features and Configurable Components (availability may vary by country)

HP ProOne 600 G4 21.5" All-in-One Business PC (Touch & Non-Touch)



1. Optical disc drive (optional)
2. SD media card reader
3. USB 2.0 or 3.1 Gen 2 Type-C™ port[1]
4. USB 3.1 Gen 1 or Gen 2 charging port[1]
5. USB 3.1 Gen 1 or Gen 2 port [1]
6. Universal Audio Jack with CTIA headset support
7. (2) USB 3.1 Gen 1 port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
8. Dual-Mode DisplayPort™ 1.2 (DP++)
9. RJ45 network connector
10. Power connector
11. Configurable I/O Port (Choice of DisplayPort™ 1.2, HDMI™ 2.0 or Serial)

1. Upgradeable to USB 3.1 Gen 2 port if configured with additional video port and/or Intel® vPro™

Standard Features and Configurable Components (availability may vary by country)

AT A GLANCE

- Choice of four form factors: Microtower, Small Form Factor, Desktop Mini, and All-in-One
- HP developed and engineered UEFI V2.6 BIOS supporting security, manageability and software image stability
- Latest Intel® 300 Series chipsets supporting latest Intel® 8 Generation Core™ processors[1], featuring integrated Intel® UHD Graphics and optional Intel® vPro™ Technology (vPro™ is optional and requires factory configuration, available with Core i5 and Core i7 processors only)[4]
- Processor support up to 65W for MT/SFF/AiO and up to 35W for Desktop Mini
- Intel® Optane memory available as optional feature
- Choice of Windows 10 Professional, Windows 10 Home, and FreeDOS 2.0
- Integrated 10/100/1000 Ethernet Controller, with optional 802.11ac Wi-Fi and/or Bluetooth® 5.0
- Up to 64 GB of DDR4 Synchronous Dynamic Random Access Memory (SDRAM) on MT and SFF, and up to 32 GB on DM and AiO
- Support for up to three video outputs via two standard video connectors and an optional third video port connector which provides the following choices: DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with Display Output on MT/SFF/DM
- Multiple data drives setup in a RAID array is optional and requires product to be configured with vPro™ at purchase on MT/SFF/DM
- Optional Serial port available on all form factors
- Optimized chassis design for SFF enabling dual 2.5" internal storage drives
- Configurable 400W PSU with VR ready[2] discrete graphics on MT
- New stylish micro-edge display bezel on All-in-One
- Trusted Platform Module (TPM) 2.0[3]
- HP SureStart Gen4
- HP BIOSphere Gen4
- HP Client Security Manager Gen4
- HP Sure Click
- HP Manageability Integration Kit Gen2
- HP Image Assistant Gen3
- HP Support Assistant
- High efficiency energy saving power supply
- ENERGY STAR® certified. EPEAT® Gold registered where applicable/supported. Registration may vary by country. See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options
- Optimized for Skype® for Business for All-in-One
- PC chassis and all internal components and modules are manufactured with low halogen content[4]
- Low halogen[4]
- Dust filter available for MT/SFF/DM
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL609501) / CSA (CSA C22.2 No.60950-1-07) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)

1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance
2. VR-ready as optional feature, requires specific configuration for support
3. In some scenarios, machines pre-configured with Windows OS might ship with TPM turned off
4 External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.
5. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependant on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with with future "virtual appliances" is yet to be determined.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Standard Features and Configurable Components (availability may vary by country)

PRODUCT NAME

HP ProDesk 600 G4 Desktop Mini Business PC
HP ProDesk 600 G4 Small Form Factor Business PC
HP ProDesk 600 G4 Microtower Business PC
HP ProOne 600 G4 21.5-inch All-in-One Business PC

OPERATING SYSTEM

Preinstalled

Windows® 10 Pro 64[1]
Windows® 10 Pro 64 (National Academic License)[1,2]
Windows® 10 Home 64[1]
Windows® 10 Home Single Language 64[1]
FreeDos 2.0

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.
2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com

CHIPSET

	DM	SFF	MT	AiO
Intel® Q370	X	X	X	X

Standard Features and Configurable Components (availability may vary by country)

PROCESSORS

Intel® 8th Generation Core™ Processors	DM	SFF	MT	AiO
Intel® Core™ i7 8700 Processor[1,] 65W 3.2 GHz base frequency Up to 4.6 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 12 MB cache, 6 cores, 12 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)[4]		X	X	X
Intel® Core™ i7+ 8700 Processor (Core i7 and Intel® Optane™)[1,2] 65W 3.2 GHz base frequency Up to 4.6 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 12 MB cache, 6 cores, 12 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rateSupports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP) [4]		X	X	X
Intel® Core™ i7 8700T Processor[1] 35W 2.4 GHz base frequency Up to 4.0 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 12 MB cache, 6 cores, 12 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP) [4]	X			X
Intel® Core™ i7+ 8700T Processor (Core i7 and Intel® Optane™)[1,2] 35W 2.4 GHz base frequency Up to 4.0 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 12 MB cache, 6 cores, 12 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP) [4]	X			X
Intel® Core™ i5 8600 Processor[1] 65W 3.1 GHz base frequency Up to 4.3 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP) [4]		X	X	X

Standard Features and Configurable Components (availability may vary by country)

	DM	SFF	MT	AiO
Intel® Core™ i5+ 8600 Processor (Core i5 and Intel® Optane™)[1,2] 65W 3.1 GHz base frequency Up to 4.3 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)[4]		X	X	X
Intel® Core™ i5 8600T Processor[1] 35W 2.3 GHz base frequency Up to 3.7 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)[4]	X			X
Intel® Core™ i5+ 8600T Processor (Core i5 and Intel® Optane™)[1,2] 35W 2.3 GHz base frequency Up to 3.7 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)[4]	X			X
Intel® Core™ i5 8500 Processor[1] 65W 3.0 GHz base frequency Up to 4.1 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)[4]		X	X	X
Intel® Core™ i5+ 8500 Processor (Core i5 and Intel® Optane™)[1,2] 65W 3.0 GHz base frequency Up to 4.1 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP)[4]		X	X	X

Standard Features and Configurable Components (availability may vary by country)

	DM	SFF	MT	AiO
Intel® Core™ i5 8500T Processor[1] 35W 2.1 GHz base frequency Up to 3.5 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP) [4]	X			X
Intel® Core™ i5+ 8500T Processor (Core i5 and Intel® Optane™)[1,2] 35W 2.1 GHz base frequency Up to 3.5 GHz max. turbo frequency with Intel® Turbo Boost Technology[3] 9 MB cache, 6 cores, 6 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2666 MT/s data rate Supports Intel® vPro™ Technology and Intel® Stable Image Platform Program (SIPP) [4]	X			X
Intel® Core™ i3 8300 Processor 62W 3.7 GHz base frequency 8 MB cache, 4 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate		X	X	X
Intel® Core™ i3 8300T Processor 35W 3.2 GHz base frequency 8 MB cache, 4 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate	X			X
Intel® Core™ i3 8100 Processor 65W 3.6 GHz base frequency 6 MB cache, 4 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate		X	X	X
Intel® Core™ i3 8100T Processor 35W 3.1 GHz base frequency 6 MB cache, 4 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate	X			X

Standard Features and Configurable Components (availability may vary by country)

Intel® 8th Generation Pentium® Processors	**DM**	**SFF**	**MT**	**AiO**
Intel® Pentium® Gold G5600 Processor 54W 3.9 GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate		X	X	X
Intel® Pentium® Gold G5500 Processor 54W 3.8 GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate		X	X	X
Intel® Pentium® Gold G5500T Processor 35W 3.2 GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® UHD Graphics 630 Supports DDR4 memory up to 2400 MT/s data rate	X			X
Intel® Pentium® Gold G5400 Processor 54W 3.7 GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® UHD Graphics 610 Supports DDR4 memory up to 2400 MT/s data rate		X	X	X
Intel® Pentium® Gold G5400T Processor 35W 3.1 GHz base frequency 4 MB cache, 2 cores, 4 threads Intel® UHD Graphics 610 Supports DDR4 memory up to 2400 MT/s data rate	X			X

Standard Features and Configurable Components (availability may vary by country)

Intel® 8th Generation Celeron™ Processors	**DM**	**SFF**	**MT**	**AiO**
Intel® Celeron® G4900 Processor 54W 3.1 GHz base frequency 2 MB cache, 2 cores, 2 threads Intel® UHD Graphics 610 Supports DDR4 memory up to 2400 MT/s data rate		X	X	X
Intel® Celeron® G4900T Processor 35W 2.9 GHz base frequency 2 MB cache, 2 cores, 2 threads Intel® UHD Graphics 610 Supports DDR4 memory up to 2400 MT/s data rate	X			X

1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
2. Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system and requires configuration with an optional Intel® Core™ i(5 or 7)+ processor.
3. Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.
4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined

NOTE: S-Processor 6+2 DDR4 2666 MT/s 2 DPC UDIMM is supported when channel is populated with the same UDIMM part number

Standard Features and Configurable Components (availability may vary by country)

GRAPHICS

Integrated Graphics	DM	SFF	MT	AiO
Intel® UHD Graphics 630 (integrated on 8th gen Core i7/i5/i3 processors and Pentium® Gold G5600, G5500, G5500T)	X	X	X	X
Intel® UHD Graphics 610 (integrated on Pentium® Gold G5400, G5400T, Celeron® G4900, G4900T)	X	X	X	X

Optional Discrete Graphics Solutions	DM	SFF	MT	AiO
AMD® Radeon™ RX550 4GB FH 2DP+HDMI			X[1]	
AMD® Radeon™ RX580 4GB FH 3DP+HDMI			X[1]	
AMD® Radeon™ R7 430 2GB DP+VGA		X	X[1]	
AMD® Radeon™ R7 430 2GB 2DP		X	X[1]	
AMD® Radeon™ 530 with 2GB GDDR5				X
NVIDIA® GeForce® GTX1060 3GB FH DVI-D+HDMI+3DP			X[1]	

AMD® Radeon™ 530 with 2GB GDDR5 must be configured at purchase

Adapters and Cables	DM	SFF	MT	AiO
HP DisplayPort™ Cable	X	X	X	X
HP DisplayPort™ to DVI-D Adapter	X	X	X	X
HP DisplayPort™ to HDMI True 4K Adapter	X	X	X	X
HP DisplayPort™ to VGA Adapter	X	X	X	X
HP USB-C™ to USB 3.0	X	X	X	X
HP USB to Serial Port Adapter	X	X	X	X
HP Type-C to DisplayPort Adapter		X	X	

1. The MT can support a single graphics card up to 75W. When configured with dual graphics cards support is limited to 35W for each.

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)	DM	SFF	MT	AiO
500 GB 7200RPM 3.5in SATA HDD		X	X	
1 TB 7200RPM 3.5in SATA HDD		X	X	
2 TB 7200RPM 3.5in SATA HDD		X	X	

2.5 inch SATA Hard Disk Drives (HDD)	DM	SFF	MT	AiO
500 GB 7200RPM 2.5in SATA HDD	X	X	X	X
1 TB 7200RPM 2.5in SATA HDD	X	X	X	X
2 TB 5400RPM 2.5in SATA HDD	X	X	X	X
500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD	X	X	X	X
500 GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD	X	X	X	X

Standard Features and Configurable Components (availability may vary by country)

2.5 inch SATA Solid State Hybrid Drives (SSHD)	DM	SFF	MT	AiO
500 GB 5400RPM 2.5in SATA SSHD	X	X	X	X
1 TB 5400RPM 2.5in SATA SSHD	X	X	X	X
2 TB 5400RPM 2.5in SATA SSHD	X		X	X

2.5 inch Solid State Drives (SSD)	DM	SFF	MT	AiO
256 GB 2.5in SATA Three Layer Cell SSD	X	X	X	X
512 GB 2.5in SATA Three Layer Cell SSD	X	X	X	X
256 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD	X	X	X	X
512 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD	X	X	X	X
256 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD	X	X	X	X
512 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD	X	X	X	X

M.2 PCIe NMVe Solid State Drives (SSD)	DM	SFF	MT	AiO
128GB M.2 2280 PCIe NVMe SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe SSD	X	X	X	X
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD		X	X	X
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD	X	X	X	X

Optical Disc Drives	DM	SFF	MT	AiO
HP 9.5mm Slim DVD-ROM Drive[1]		X	X	X
HP 9.5mm Slim DVD Writer Drive[2]		X	X	X
HP 9.5mm Slim Blu-Ray Writer Drive[3]		X	X	X

1. HD-DVD disks cannot be played on this drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.
2. Don't copy copyright-protected materials.
3. With Blu-Ray, certain disc, digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this Desktop PC.

Media Card Reader	DM	SFF	MT	AiO
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I, UHS-II)		X	X	
SD 3.0 with 4-in-1 Interface (Supports SD, SDXC, SDHC, UHS-I)				X

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

MEMORY

	DM	SFF	MT	AiO
DDR4-2666 (Transfer rates up to 2666 MT/s), 32 GB, 2 SODIMM	X			X
DDR4-2666 (Transfer rates up to 2666 MT/s), 64 GB, 4 DIMM		X	X	

Memory Configuration

4 GB (4 GB x 1)	X	X	X	X
8 GB (4 GB x 2)	X	X	X	X
8 GB (8 GB x 1)	X	X	X	X
16 GB (8 GB x 2)	X	X	X	X
16 GB (16 GB x 1)	X	X	X	X
32 GB (16 GB x 2)	X	X	X	X
32 GB (8 GB x 4)		X	X	
64 GB (16 GB x 4)		X	X	

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.
Memory modules support data transfer rates up to 2666 MT/s; actual data rate is determined by the system's configured processor and memory configuration. See processor specifications for supported memory data rate.
NOTE: All memory slots are customer accessible / upgradeable.
NOTE: S-Processor 6+2 DDR4 2666 MT/s 2 DPC UDIMM is supported when channel is populated with the same UDIMM part number.

NETWORKING/COMMUNICATIONS[1]

Ethernet (RJ-45)	DM	SFF	MT	AiO
Intel® I219-LM Gigabit Network Connection (standard)	X	X	X	X
Intel® I210-T1 PCIe x1 Gigabit Network Interface Card (optional)		X	X	

Wireless[1]

Intel® 9560 802.11ac 2x2 with Bluetooth® M.2 Combo Card vPro™	X	X	X	X
Intel® 9560 802.11ac 2x2 with Bluetooth® M.2 Combo Card non-vPro™	X	X	X	X
Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card	X	X	X	X
Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card	X	X	X	X

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices

Standard Features and Configurable Components (availability may vary by country)

KEYBOARDS AND POINTING DEVICES

Keyboards	DM	SFF	MT	AiO
HP PS/2 Business Slim Standalone Wired Keyboard		X	X	
HP USB Business Slim Standalone Wired Keyboard	X	X	X	X
HP USB Business Slim Wired SmartCard CCID Keyboard	X	X	X	X
HP USB & PS/2 Washable Standalone Wired Keyboard	X	X	X	X
HP Premium Standalone Wireless Keyboard		X	X	
HP Collaboration Wireless Keyboard	X	X	X	X
HP USB Collaboration Wired Keyboard	X	X	X	X
HP USB Conferencing Wired Keyboard	X	X	X	X
HP USB Wired Keyboard	X	X	X	X
Standalone Wired Keyboard Value		X	X	X

Keyboard & Mouse Combo	DM	SFF	MT	AiO
HP Premium Wireless Keyboard and Mouse	X	X	X	X
HP Premium USB Wired Keyboard and Mouse		X	X	
HP Business Slim Wireless Keyboard and Mouse	X	X	X	X
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X
HP USB Keyboard and Mouse Wired Value	X			X
HP USB PS/2 Washable Keyboard and Mouse Wired		X	X	

Mouse	DM	SFF	MT	AiO
HP USB Universal Wired Mouse	X			X
HP PS/2 Mouse		X	X	
HP USB Optical Mouse	X	X	X	X
HP USB Hardened Mouse	X	X	X	X
HP USB 1000dpi Laser Mouse	X	X	X	X
HP USB & PS/2 Washable Wired Mouse Standalone	X	X	X	X
HP USB Premium Wired Mouse	X	X	X	

NOTE: Availability may vary by country

Standard Features and Configurable Components (availability may vary by country)

SECURITY

	DM	SFF	MT	AiO
Trusted Platform Module (TPM) 2.0 (Infineon SLB9670). Common Criteria EAL4+ Certified. Convertible to FIPS 140-2 Certified mode.	X	X	X	X
Solenoid Lock & Intrusion Sensor			X	
Intrusion Sensor (Optional)		X		X
Intrusion Sensor for DM (integrated in the PCA, can be enabled/disabled through BIOS)	X			
Support for chassis cable lock devices	X	X	X	X
Support for chassis padlocks devices	X	X	X	
Support for table lock				X
SATA port disablement (via BIOS)	X	X	X	X
Serial, USB enable / disable (via BIOS)	X	X	X	X
Intel® Identify Protection Technology (IPT)[1]	X	X	X	X
Removable media write/boot control	X	X	X	X
Power-on password (via BIOS)	X	X	X	X
Setup password (via BIOS)	X	X	X	X

1. Models configured with Intel® Core™ processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module

PORTS

Internal Slots and Ports	DM	SFF	MT	AiO
M.2 PCIe	(1) M.2 PCIe x1 2230 (for WLAN) (2) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x4 2280/2230 Combo (for storage)	(1) M.2 PCIe x1 2230 (for WLAN) (1) M.2 PCIe x4 2280/2230 Combo (for storage)
PCI Express v3.0 x1			2[1]	
PCI Express v3.0 x4		1		
PCI Express v3.0 x16 (wired as x4)			1	
PCI Express v3.0 x16		1	1	
PCI x1[1]			1	
SATA port		3	4	
DM SATA storage connector	1			
AiO SATA storage connector				1

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Standard Features and Configurable Components (availability may vary by country)

Bays	DM	SFF	MT	AiO
5.25" Half Height			1[4]	
9mm Slim Optical Disc Drive (ODD)		1	1[4]	1[2]
SD Card Reader		1	1	1
2.5" Internal Storage Drive	1	2[3]	2[4]	1
3.5" Internal Storage Drive		1	1[4]	

User Accessible Ports	DM	SFF	MT	AiO
USB 2.0		2 (front) 2 (rear)	2 (front) 2 (rear)	
USB Type-C 2.0				1 (side)[5]
USB 3.1 Gen 1	1 (front) 2 (rear)	2 (rear)	2 (rear)	2 (side)[5] 2 (rear)
USB 3.1 Gen 2	1 (front) 2 (rear)	2 (front) 2 (rear)	2 (front) 2 (rear)	
USB Type-C 3.1 Gen 2	1 (front) 1 (rear) (optional)	1 (front) 1 (rear) (optional)	1 (front) 1 (rear) (optional)	
Video	2 DisplayPort™ 1.2 (rear) 1 Optional configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with display output)	2 DisplayPort™ 1.2 (rear) 1 Optional configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with display output)	2 DisplayPort™ 1.2 (rear) 1 Optional configurable video port (rear) (Choice of DisplayPort™ 1.2, HDMI™ 2.0, VGA, or USB Type-C™ with display output)	1 DisplayPort™ 1.2 (rear) 1 Optional configurable video port (rear) (Choice of DisplayPort™ 1.2 or HDMI™ 2.0)
Audio	1 Headphone (front) 1 Universal Audio Jack with CTIA headset support (front)	Front: 1 Headset Rear: 1 Audio-out 1 Audio-in	Front: 1 Headset Rear: 1 Audio-out 1 Audio-in	1 Universal Audio Jack with CTIA headset support (side)
Network Interface	RJ45	RJ45	RJ45	RJ45
Serial (RS-232)	1 (rear) (optional)	2 (rear) (optional)	2 (rear) (optional)	1 (rear) (optional)

1. On certain models, it would be (1) PCI Express x1 and (1) PCI x1. Maximum total of 4 PCI/PCIe slots supported on MT.
2. Must be configured at time of purchase
3. SFF can be configured with either (1) 3.5" or (2) 2.5" internal storage drive (2.5-inch drive needs adapter)
4. Configuration options will be (1) 5.25" internal half-height drive bay or (2) 2.5" internal storage drive bays, (1) 3.5" internal storage drive bay, (1) 9.5mm internal optical drive bay
5. Upgradeable to USB 3.1 Gen 2 port 10 Gb/s signaling data rate* if configured with additional video port and/or Intel® vPro™

*Actual throughput may vary.

Standard Features and Configurable Components (availability may vary by country)

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Preinstalled Software
HP BIOSphere Gen4[17]
HP DriveLock & Automatic DriveLock
BIOS Update via Network

Master Boot Record Security
Power On Authentication
Absolute Persistence Module[19]
Pre-boot Authentication
HP Wireless Wakeup
Software
HP Native Miracast Support[15]
HP ePrint Driver + JetAdvantage[20]
HP Hotkey Support
HP Recovery Manager
HP Jumpstart
HP Support Assistant[21]
HP Noise Cancellation Software
HP PhoneWise[29]
Buy Office (sold separately)
Manageability Features
HP Driver Packs[22]
HP System Software Manager (SSM)
HP BIOS Config Utility (BCU)

HP Client Catalog
HP Manageability Integration Kit Gen2[23]
Ivanti Management Suite[24]

Client Security Software
HP Client Security Manager Gen4[25] including:
HP Security Manager[26] (including Credential Manager, HP Password Manager, HP Spare Key)
HP Device Access Manager
HP Power On Authentication
Microsoft Defender[27]

Security Management
HP Secure Erase[18]
RAID configurations[33]
USB enable/disable (via BIOS)
Power-on password (via BIOS)
Setup password (via BIOS)
Support for chassis padlocks and cable lock devices
Integrated hood sensor
HP Sure Click[37]
HP Sure Start Gen4[30]

15. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming
17. HP BIOSphere Gen4 features may vary depending on the PC platform and configurations requires 8th Gen Intel® processors.
18. Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88.
19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain

Standard Features and Configurable Components (availability may vary by country)

conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.
20. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see www.hp.com/go/eprintcenter). Print times and connection speeds may vary.
21. HP Support Assistant requires Windows and Internet access.
22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
23. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
24. Ivanti Management Suite subscription required.
25. HP Client Security Suite Gen 4 requires Windows and Intel® or AMD 8th generation processors.
26. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
27. Microsoft Defender Opt in and internet connection required for updates.
29. For supported platforms and HP Phonewise system requirements see: http://www.hp.com/go/HPPhonewise.
30. HP Sure Start Gen4 is available on HP ProDesk & ProOne products equipped with Intel® 8th generation processors
33. RAID configuration is optional and does require a second hard drive.
37. HP Sure Click is available on select HP platforms and supports Microsoft® Internet Explorer and Chromium™. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available

Standard Features and Configurable Components (availability may vary by country)

ENVIRONMENTAL & INDUSTRY

HP Prodesk 600 G4 Desktop Mini Business PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • TCO Certified		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	4.81 W	4.90 W	4.67 W
Normal Operation (Long idle)	4.37 W	4.39 W	4.29 W
Sleep	0.56 W	0.60 W	0.55 W
Off	0.52 W	0.55W	0.52 W
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	16 BTU/hr	17 BTU/hr	16 BTU/hr
Normal Operation (Long idle)	15 BTU/hr	15 BTU/hr	15 BTU/hr
Sleep	2 BTU/hr	2 BTU/hr	2 BTU/hr
Off	2 BTU/hr	2 BTU/hr	2 BTU/hr
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured – Idle	3.1	19	
Fixed Disk – Random writes	3.1	20	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station		

Standard Features and Configurable Components (availability may vary by country)

	• 1 multi-bay II storage port • Interchangeable HDD Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Corrugated	322 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	33 g
		PLASTIC/Polyethylene low density - LDPE	5 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		

Standard Features and Configurable Components (availability may vary by country)

Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP ProDesk 600 G4 Small Form Factor Business PC

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • TCO Certified		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a Typically Configured Notebook.		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	13.16 W	12.72 W	12.86 W
Normal Operation (Long idle)	11.89 W	11.86 W	11.93 W
Sleep	1.04 W	1.05W	1.03 W
Off	0.91 W	0.92 W	0.91 W

Standard Features and Configurable Components (availability may vary by country)

	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 60Hz**
Normal Operation (Short idle)	45 BTU/hr	43 BTU/hr	44 BTU/hr
Normal Operation (Long idle)	41 BTU/hr	40 BTU/hr	41 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	3 BTU/hr	3 BTU/hr	3 BTU/hr
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured – Idle	3.2	22	
Fixed Disk – Random writes	3.2	22	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: • 3 USB ports • 1 PC card slot (type I/II) • 1 ExpressCard/54 slot • 1 IEEE 1394 Port • 2 SODIMM memory slots • Optional expansion base docking station • 1 multi-bay II storage port • Interchangeable HDD Spare parts are available throughout the warranty period and or for up to 5 years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.)		

Standard Features and Configurable Components (availability may vary by country)

	• This product is 95.1% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Corrugated	1170 g
	Internal:	PAPER/Paper	17 g
		PLASTIC/Polyethylene low density - LDPE	378 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.		
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.		

Standard Features and Configurable Components (availability may vary by country)

	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP ProDesk 600 MicroTower G4 series

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • TCO Certified		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	13.599	13.514	13.099
Normal Operation (Long idle)	12.211	11.765	12.367
Sleep	1.318	1.312	1.322
Off	0.616	0.618	0.618
	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)	46.3726	46.0827	44.6676
Normal Operation (Long idle)	41.6395	40.1187	42.1715
Sleep	4.4944	4.4739	4.508
Off	2.1006	2.1074	2.1074
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured – Idle	4	29	
Fixed Disk – Random writes	4.4	33	

Standard Features and Configurable Components (availability may vary by country)

Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, See http://www.epeat.net for registration status by country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Corrugated	
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	
		PLASTIC/Polyethylene low density	
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		

Standard Features and Configurable Components (availability may vary by country)

Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP ProDesk 600 All-in-One G4 series

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: • IT ECO declaration • US ENERGY STAR® • EPEAT® Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword generator on HP's 3rd party option store for solar generator accessories at http://www.hp.com/go/options. • TCO Certified		
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the Desktop model is based on a "Typically Configured Desktop".		
Energy Consumption (in accordance with US ENERGY STAR® test method)	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			

Standard Features and Configurable Components (availability may vary by country)

	NOTE: Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.		
Heat Dissipation*	**115VAC, 60Hz**	**230VAC, 50Hz**	**100VAC, 50Hz**
Normal Operation (Short idle)			
Normal Operation (Long idle)			
Sleep			
Off			
	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.		
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound Power (L_{WAd}, bels)	Sound Pressure (L_{pAm}, decibels)	
Typically Configured – Idle	4.3	32	
Fixed Disk – Random writes	4.4	33	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Batteries	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater than 1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell) Battery type: Lithium		
Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. • This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. • This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). • This product is in compliance with the IEEE 1680 (EPEAT) standard at the <gold> level, see http://www.epeat.net • Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043. • This product contains 0% post-consumer recycled plastic (by wt.) • This product is 95.1% recycle-able when properly disposed of at end of life.		
Packaging Materials	**External:**	PAPER/Corrugated	
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	
		PLASTIC/Polyethylene low density	
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos		

Standard Features and Configurable Components (availability may vary by country)

	• Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. • Ozone Depleting Substances • Polybrominated Biphenyls (PBBs) • Polybrominated Biphenyl Ethers (PBBEs) • Polybrominated Biphenyl Oxides (PBBOs) • Polychlorinated Biphenyl (PCB) • Polychlorinated Terphenyls (PCT) • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. • Radioactive Substances • Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging: • Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. • Eliminate the use of ozone-depleting substances (ODS) in packaging materials. • Design packaging materials for ease of disassembly. • Maximize the use of post-consumer recycled content materials in packaging materials. • Use readily recyclable packaging materials such as paper and corrugated materials. • Reduce size and weight of packages to improve transportation fuel efficiency. • Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

Standard Features and Configurable Components (availability may vary by country)

SERVICE AND SUPPORT

On-site Warranty[1]: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day[2] service for parts and labor and includes free support 24 x 7[3]. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.[4]

1. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.
2. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
3. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.
4. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

Standard Features and Configurable Components (availability may vary by country)

PROCESSORS

Intel® 8th Generation Core™ Processors

All HP ProDesk & ProOne 600 G4 Business PC models featuring this technology include processors that are part of the Intel® Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP ProDesk and ProOne 600 G4 Business PC.

Intel® Advanced Management Technology (AMT) v12[1] – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework

1. Intel® Active Management Technology requires an Intel® AMT-enabled chipset, network hardware and software, as well as connection with a power source and a corporate network connection. Setup requires configuration by the purchaser and may require scripting with the management console or further integration into existing security frameworks to enable certain functionality. It may also require modifications of implementation of new business processes.

Standard Features and Configurable Components (availability may vary by country)

DISPLAY PANEL SPECIFICATIONS[1]

HP ProOne 600 G4 AIO

21.5" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080)
Non-touch or optional touch
Projected Capacitive Touch supports up to 10 touch-points

Type	IPS WLED Backlit LCD
Active area (mm)	476.064 x 267.786
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.24795 x 0.24795
Contrast ratio (typical)	1000:1
Brightness (typical)	250nits
Viewing angle (typical) (HxV)	178 ° x 178 °
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut (typical)	NTSC 72%
Anti-glare	Yes
Default color temperature	Warm (6500K)

1. All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Standard Features and Configurable Components (availability may vary by country)

GRAPHICS

Intel® UHD Graphics (integrated)

Graphics Controller	Integrated
DisplayPort™	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI
VGA	VGA output
USB-C™ DP Alt Mode	DisplayPort™ over the USB-C™ module
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12

AMD® Radeon™ R7 430 2 GB DP+VGA

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB (128-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution (VGA)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2 GB 2DP

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(128-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes

Standard Features and Configurable Components (availability may vary by country)

Rear I/O connectors(bracket)	2DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

NVIDIA® GeForce® GTX1060 3 GB FH DVI-D+HDMI+3DP

Engine Clock	1506 MHz
Memory Clock	4004 MHz
Memory Size(width)	3 GB(192-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	5120x3200@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DVI-D+HDMI+3DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<120W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ RX550 4GB FH 2DP+HDMI

Engine Clock	1183MHz
Memory Clock	7 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	2DP+HDMI
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<62W
PCB form-factor with bracket	ATX (Full height) PCB with ATX single slot bracket

Standard Features and Configurable Components (availability may vary by country)

AMD® Radeon™ RX580 4 GB FH 3DP+HDMI

Engine Clock	1266 MHz
Memory Clock	8 Gbps
Memory Size(width)	4 GB(256-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	5120x3200@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	3DP+HDMI
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<150W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

AMD Radeon™ 530 with 2 GB GDDR5

Memory	2 GB 64-bit wide frame buffer operating at 1125MHz.
Controller Clock Speed	AMD Radeon™ 530 GPU operating at 1024 MHz
Architecture	Hybrid Graphics AMD GPU uses Intel graphics controller for display control
Bus Connection	PCIE 3.0 x8
Graphics /API support	DIRECTX 12, Open GL 4.5, Open CL2.0, UVD
Display support	Same as for the Intel integrated graphics solution

Standard Features and Configurable Components (availability may vary by country)

HARD DISK AND SOLID STATE STORAGE

500GB 7200RPM 3.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	16 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

1 TB 7200RPM 3.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	64 MB
Seek Time	11 ms (Average)
Height	1.028 in/26.11 mm
Width	4.0 in/101.6 mm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in SATA HDD

Capacity	500GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	16 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 2.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	1,953,525,168
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA HDD

Capacity	2 TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	128MB
Logical Blocks	3,907,050,336
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity	500 GB
Rotational Speed	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity	500 GB
Rotational Speed	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 5400RPM 2.5in SATA SSHD

Capacity	500 GB
Rotational Speed	5,400 rpm
Drive Type	Solid State Hybrid Drive (SSHD) technology with NAND Flash
Interface	SATA 6 Gb/s
Buffer Size	64 MB
NAND Flash	8GB
Seek Time	12 ms (Average)
Height	0.267 in/6.8 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 5400RPM 2.5in SATA SSHD

Capacity	1 TB
Rotational Speed	5,400 rpm
Drive Type	Solid State Hybrid Drive (SSHD) technology with NAND Flash
Interface	SATA 6 Gb/s
Buffer Size	64 MB
NAND Flash	8GB
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA SSHD

Capacity	2TB
Rotational Speed	5,400 rpm
Drive Type	Solid State Hybrid Drive (SSHD) technology with NAND Flash
Interface	SATA 6 Gb/s
Buffer Size	128 MB
NAND Flash	8GB
Seek Time	12 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<50g
Capacity	128 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 70K/40K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 380MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

256 GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<62g
Capacity	256 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 55K/68K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 450MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB 2.5in SATA Three Layer Cell SSD

Drive Weight	<50g
Capacity	512 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 92K/83K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	<50g
Capacity	256 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 55K/80K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM; TCG-OPAL2.0 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB 2.5in SATA Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	<50g
Capacity	512 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 92K/83K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM; TCG-OPAL2.0 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD

Drive Weight	<40g
Capacity	256 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 55K/83K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM; FIPS 140-2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB 2.5in SATA Self Encrypted Federal Information Processing Standard SSD

Drive Weight	<45g
Capacity	512 GB
Height	7mm
Length	100.45mm
Width	69.85mm
Interface	SATA 3.0 (6Gb/s)
Performance	Up to Random Read/Write = 92K/83K IOPS
Maximum Sequential Read	Up to 530MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	DIPM; TRIM; FIPS 140-2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

128 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	128 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 60K/50K IOPS
Maximum Sequential Read	Up to 1400MB/s
Maximum Sequential Write	Up to 395MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 120K/170K IOPS
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 200K/180K IOPS
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 140K/40K IOPS
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 150K/180K IOPS
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 270K/235K IOPS
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

Standard Features and Configurable Components (availability may vary by country)

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 290K/240K IOPS
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 2100MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 150K/180K IOPS
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Performance	Up to Random Read/Write = 270K/235K IOPS
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Slim DVD-ROM Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	Up to 0.31 lb (140g) without bezel
Read Speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X
Access time (typical reads, including settling)	Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.31 lb (140 g)
Read Speeds	DVD-R DL - Up to 6X DVD+R - Up to 8X DVD+RW - Up to 8X DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+RW - Up to 8X DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Disc recording capacity	Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	0.29 lb (132 g)
Write Speeds	BD-R Up to 4X BD-RE Up to 2X BD-R Up to 6X BD-RE Up to 2X DVD-R Up to 8X DVD-RW Up to 6X DVD+R Up to 8X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X
Read Speeds	BD-R Up to 6X BD-RE Up to 4X BD-ROM Up to 6X BD-R Up to 6X BD-RE Up to 6X DVD-ROM Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R Up to 8X DVD+RW Up to 8X BDMV (AACS Compliant Disc) Up to 6x/2x (Read/Play) DVD-RAM Up to 5x DVD-Video (CSS Compliant Disc) Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x CD-DA (DAE) Up to 24X/10X (Read/Play)
Access time (typical reads, including settling)	Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical), CD-ROM: 165 ms (typical) Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical), CD-ROM: 340 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC -1200 mA typical, 2000 mA maximum
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

Standard Features and Configurable Components (availability may vary by country)

NETWORKING AND COMMUNICATIONS

Intel® I219-LM Gigabit Network Connection (standard)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K
Power consumption	Cable Disconnection: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® I210-T1 PCIe x1 Gigabit Network Interface Card (optional)	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload (ARP & NS) Large send offload and Giant send offload Receiving Side Scaling Jumbo Frame 9K

Standard Features and Configurable Components (availability may vary by country)

Power consumption	Cable Disconnetion: 25mW 100Mbps Full Run: 450mW 1000bp Full Run: 1000mW WoL Enable(S3/S4/S5): 50mW WoL Disable(S3/S4/S5): 25mW
Power Management	ACPI compliant – multiple power modes Situation-sensitive features reduce power consumption Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® 9560 802.11ac 2x2 with Bluetooth® M.2 Combo Card vPro™	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum

Standard Features and Configurable Components (availability may vary by country)

	• 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum	
Power Consumption	• Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)	
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW	

Standard Features and Configurable Components (availability may vary by country)

Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® 9560 802.11ac 2x2 with Bluetooth® M.2 Combo Card non-vPro™	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, , 80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
Security	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification

Standard Features and Configurable Components (availability may vary by country)

	• IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum	
Power Consumption	• Transmit mode2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2/5.0 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2/5.0 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps	
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels	

Standard Features and Configurable Components (availability may vary by country)

	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek RTL8822BE 802.11ac 2x2 with Bluetooth® M.2 Combo Card	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz)
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

Standard Features and Configurable Components (availability may vary by country)

Security	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power	• 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum	
Power Consumption	• Transmit mode2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230: 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230: 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module with Bluetooth 4.0/4.1/4.2 Wireless Technology		
Bluetooth® Specification	4.0/4.1/4.2 Compliant	
Frequency Band	2402 to 2480 MHz	

Standard Features and Configurable Components (availability may vary by country)

Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Realtek RTL8821CE 802.11ac 1x1 with Bluetooth® M.2 Combo Card	
Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n • 2.402 – 2.482 GHz 802.11a/n • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

Standard Features and Configurable Components (availability may vary by country)

	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)	
Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM	
Security	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • IEEE 802.11i • Cisco Certified Extensions, all versions through CCX4 and CCX Lite • WAPI	
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power	• 802.11b : +14dBm minimum • 802.11g : +12dBm minimum • 802.11a : +12dBm minimum • 802.11n HT20(2.4GHz) : +12dBm minimum • 802.11n HT40(2.4GHz) : +12dBm minimum • 802.11n HT20(5GHz) : +10dBm minimum • 802.11n HT40(5GHz) : +10dBm minimum • 802.11ac VHT80(5GHz) : +10dBm minimum	
Power Consumption	• Transmit mode2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW	
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode	
Receiver Sensitivity	802.11b, 1Mbps : -93.5dBm maximum 802.11b, 11Mbps : -84dBm maximum 802.11a/g, 6Mbps : -86dBm maximum 802.11a/g, 54Mbps : -72dBm maximum 802.11n, MCS07 : -67dBm maximum 802.11n, MCS15 : -64dBm maximum 802.11ac, MCS0 : -84dBm maximum 802.11ac, MCS9 : -59dBm maximum	
Antenna type	High efficiency antenna. One embedded dual band 2.4/5 GHz antenna is provided to the card to support WLAN communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm	
Weight	Type 2230 : 2.8g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating Non-operating	14° to 158° F (–10° to 70° C) –40° to 176° F (–40° to 80° C)
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)
Altitude	Operating Non-operating	0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio OFF; LED White – Radio ON	
HP Integrated Module with Bluetooth® 4.0/4.1/4.2 Wireless Technology		

Standard Features and Configurable Components (availability may vary by country)

Bluetooth® Specification	4.0/4.1/4.2 Compliant
Frequency Band	2402 to 2480 MHz
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Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +4 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW
Electrical Interface	USB 2.0 compliant
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Standard Features and Configurable Components (availability may vary by country)

I/O DEVICES

HP USB Business Slim Standalone Wired Keyboard		
Physical Characteristics	Keys	104, 105, 106, 107, 109 layout (depending upon country)
	Dimensions (L x W x H)	171.97 x 68.35 x 8.27 in (436.8± 1.5 x 137.6± 1.0 x 21.0± 1.0 cm)
	Weight	1.32 lb (0.6± 0.08 kg)
Electrical	Operating voltage	4.4-5.25VDC
	Power consumption	50-mA maximum (with 5 VDC power supplied and three LEDs ON)
	System interface	USB or PS/2
	ESD	Contact Discharge: 2, 4,6,8KV Air Discharge: 2, 4, 8,10,12.5KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±12.5g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	Minus 30 degrees to 60 degrees Celsius
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP USB Business Slim Wired SmartCard CCID Keyboard		
Physical Characteristics	Keys	104, 105, 109 layout (depending upon country)
	Dimensions (L x W x H)	17.34 x 5.68 x 0.78in (440.6 x 144.5 x 1.98 cm)
	Weight	1.32 lb (598g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	100mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 12.5 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	CE Marking, TUV, EAC, FCC, cULus/CSAus, ICES, RCM, VCCI, KCC, BSMI, KCC, EAC, ICES, RCM	
Ergonomic compliance	ISO 9241-4, TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP USB & PS/2 Washable Standalone Wired Keyboard		
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	17.68 x 6.68 x 1.22 in (449.18 x 169.66 x31.2 mm)
	Weight	1.57 lb (710g)
Electrical	Operating voltage	5V +- 5%
	Power consumption	50mA
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	55±10g nominal peak force with tactile feedback
	Switch life	20 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	7.2 ft (2.2 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-4° to 149° F (-20° to 65° C)
	Operating humidity	10% to 95% (non-condensing at ambient)
	Non-operating humidity	0% to 95% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, cUL, FCC, CE, TUV GS, VCCI, BSMI, C-Tick, KCC, USB-IF, WHQL, EN/IEC 60601-1, IP66/NEMA4X	
Ergonomic compliance	ANSI HFS 100, ISO 9241-4, and TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP Premium Standalone Wireless Keyboard		
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.54 lb (698g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	35mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC	
Ergonomic compliance	TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP USB Premium Wired Keyboard		
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.54 lb (698g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	35mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC	
Ergonomic compliance	TUVGS	

Standard Features and Configurable Components (availability may vary by country)

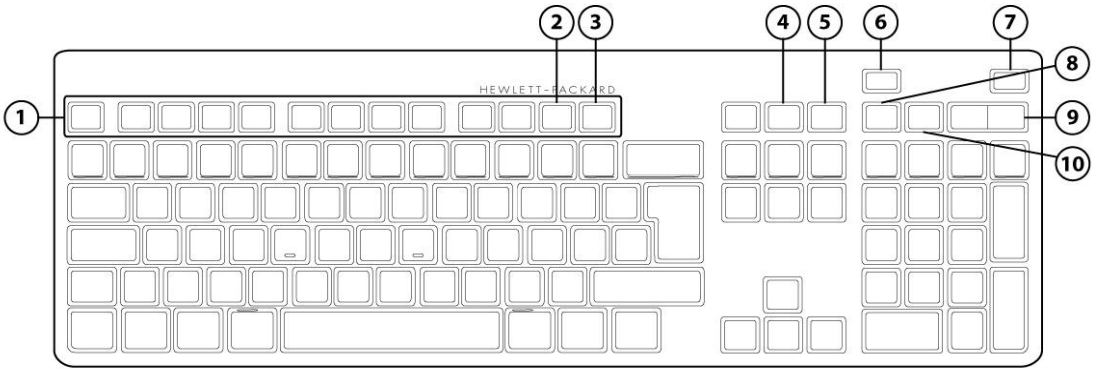
HP Collaboration Wireless Keyboard		
Physical Characteristics	Keys	109,110 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.54lb (700g)
Electrical	Operating voltage	4.2VDC, +/-5%
	Power consumption	70mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 85% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, VCCI, BSMI, KCC, EAC, ICES, RCM, EMC	
Ergonomic compliance	TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP USB Collaboration Wired Keyboard		
Physical Characteristics	Keys	109,110 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.48 lb (670g)
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	70mA (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 85% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, VCCI, BSMI, KCC, EAC, ICES, RCM, EMC	
Ergonomic compliance	TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP USB Conferencing Wired Keyboard



1. Function Keys
2. F11 Lync or Skype for Business Contact list[1]
3. F12 Lync or Skype for Business Calendar[2]
4. Share Screen
5. Stop Webcam
6. End/Decline a Call
7. Answer a Call
8. Microphone Mute
9. Volume Up/Down
10. Audio Mute

1. Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Contact list
2. Microsoft Lync 2013, or Skype for Business, or Microsoft Outlook 2013 Calendar

Standard Features and Configurable Components (availability may vary by country)

HP USB Wired Keyboard		
Physical Characteristics	Keys	104, 105, 106, 108, 109 layouts
	Dimensions (L x W x H)	18.12 x 6.47 x 1.10 in (460.28 x 164.31 x 27.88 mm)
	Weight	1.98 lb (900g) min
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	60±14g nominal peak force with tactile feedback
	Switch life	20 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	CUL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC	
Ergonomic compliance	TUVGS	

Standard Features and Configurable Components (availability may vary by country)

Standalone Wired Keyboard Value		
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	18.15 x 6.02 x 1.08 in (461 x 153 x 27.4 mm)
	Weight	1.32 lb (600g) min
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	50mA Max (All LED on)
	System interface	USB Type A plug connector
	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Mid-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
Environmental	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC	
Ergonomic compliance	TUVGS	

Standard Features and Configurable Components (availability may vary by country)

HP USB Keyboard Healthcare Edition		
Physical Characteristics	Keys	98 (US Layout), 99(EU Layout)
	Dimensions (L x W x H)	13.6x4.5x1.0 in (345x115x25 mm) (L x W x H)
	Weight	0.7 lbs (307 g)
Electrical	Operating voltage	4.75 to 5.25VDC
	Power consumption	100-mA maximum
	System interface	USB Type A plug connector
	ESD	Contact Discharge: ±4 KV Air Discharge: ±8KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
Mechanical	Keycaps	Low-profile design
	Switch actuation	55±10g nominal peak force with tactile feedback
	Switch life	8 million keystrokes (Life tester)
	Switch type	Membrane switch
	Key-leveling mechanisms	N/A
	Cable length	1820+30/-20mm 6 ft (1.8 m)
Environmental	Acoustics	<40-dBA maximum sound pressure level
	Operating temperature	32° to 122° F (0° to 50° C)
	Non-operating temperature	23° to 131° F (-5° to 55° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 90% (non-condensing at ambient)
	Operating shock	NA
	Non-operating shock	NA
	Operating vibration	NA
	Non-operating vibration	NA
	Drop (out of box)	30 in (76 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76 cm) on steel, 10-drop sequence
Approvals	FCC, CE Mark, C-Tick, ICES-003 and IP65.	
Ergonomic compliance	N/A	

Standard Features and Configurable Components (availability may vary by country)

HP USB Universal Wired Mouse		
Dimensions (H x L x W)	4.53 x 2.50 x 1.40 in (115 x 63.46 x 35.48 mmm)	
Weight	0.18lb (80g)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption (typical)	50mA Max
	Resolution	1,000 DPI
	Sensor	Pixart PAN3606DL
	Tracking speed	30 inch/sec (max)
	Tracking acceleration	9G(max), 1G=9.8m/s2
Mechanical	Connector	USB 2.0
	Cable length	6 ft (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC

Standard Features and Configurable Components (availability may vary by country)

HP USB Optical Mouse		
Dimensions (H x L x W)	4.53 x 2.48 x1.46 in (115.2x 63 x37 mm)	
Weight	0.22lb (101.6g)	
Environmental	Operating temperature	41° to 122° F (5° to 50° C)
	Non-operating temperature	(-4° to 140° F)(-20° to 60° C)
	Operating humidity	10% to 85% (non-condensing at ambient)
	Non-operating humidity	5% to 95% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Tracking speed	30 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s2
	System interface	USB or PS/2
Mechanical	Switch actuation	60±15g nominal peak force with tactile feedback
	Switch life	3 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC

Standard Features and Configurable Components (availability may vary by country)

HP USB 1000dpi Laser Mouse		
Dimensions (H x L x W)	115 * 62.9 * 37 mm (L * W * H)	
Weight	0.22lb (101.6g)	
Environmental	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption (typical)	100mA
	Resolution	1,000 DPI
	Sensor	PixArt vendor Laser USB mouse sensor
	Tracking speed	30 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s2
Mechanical	Connector	USB 2.0
	Cable length	6 ft (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC, EAC

Standard Features and Configurable Components (availability may vary by country)

HP USB Premium Wired Mouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x 38.7 mmm)	
Weight	0.19lb (90g)	
Environmental	Operating temperature	50° to 122°F (10° to 50° C)
	Non-operating temperature	-22° to 140°F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2 g peak acceleration
	Non-operating vibration	4 g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption (typical)	12mA
	Resolution	800, 1200, 1600 DPI
	Sensor	Pixart PAN3606DL
	Tracking speed	30 inch/sec (max)
	Tracking acceleration	8G(max), 1G=9.8m/s2
Mechanical	Connector	USB 2.0
	Cable length	6 ft (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, C-Tick, KC

AUDIO/MULTIMEDIA

HP ProDesk 600 G4 Desktop Mini Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

Standard Features and Configurable Components (availability may vary by country)

HP ProDesk 600 G4 Small Form Factor Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port 1 - Headphone port Rear: Line-out Line-in All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP ProDesk 600 G4 Microtower Business PC

Type	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port Rear: Line-Out Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming allows independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

Standard Features and Configurable Components (availability may vary by country)

HP ProOne 600 G4 AIO PC

Type	Integrated
HD Stereo Codec	Conexant CX3601
Audio I/O Ports	Side 3.5mm headset connector supports an OMTP or CTIA style headset and is re-taskable as a Line-in, Line-out, Microphone-in or Headphone-out port
Internal Speaker Amplifier	2W per channel class D stereo amplifier for the internal speakers only
Multi-streaming Capable	Playback multi-streaming allows independent audio streams to be sent to/from the side jack and integrated speakers.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes - Stereo

INTEGRATED WEBCAM AND MICROPHONE

Optional integrated 1 MP HD RGB webcam & microphone; maximum resolution of 1280 x 720
Optional integrated 2 MP Full HD RGB webcam & microphone; maximum resolution of 1920 x 1080
Optional integrated 2 MP Full HD RGB webcam with IR sensor & microphone; maximum resolution of 1920 x 1080

Standard Features and Configurable Components (availability may vary by country)

POWER

HP ProDesk 600 G4 Desktop Mini Business PC

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)

HP ProDesk 600 G4 Small Form Factor Business PC

Unit Environment and Operating Conditions

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating : 5°C ~50°C Non-Operating : -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft (15240 m)

Standard Features and Configurable Components (availability may vary by country)

HP ProDesk 600 G4 Microtower Business PC

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5°C ~45°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft (15240 m)

HP ProOne 600 G4 AIO PC

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft (15240 m)

Standard Features and Configurable Components (availability may vary by country)

	DM	SFF	MT	AiO
External Power Supplies	65W EPS, 89% average efficiency at 115V & 230Vac	N/A	N/A	90W EPS, 89% average efficiency at 115V & 230Vac 120W EPS, 89% average efficiency at 115V & 230Vac
80 PLUS Platinum	N/A	180W active PFC 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	250W active PFC / 80 PLUS Platinum 400W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	N/A
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
Operating Line Frequency	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current	≦1.6A	≦2.3A	250W≦3A 400W≦5.2A	90W≦1.2A 120W≦2.2A
Rated Input Current with Energy Efficient* Power Supply	≦1.6A	≦2.3A	250W≦3A 400W≦5.2A	90W≦1.2A 120W≦2.2A
DC Output	+19.5V	+12V	+12V	+19.5V

Standard Features and Configurable Components (availability may vary by country)

	DM	SFF	MT	AiO
Current Leakage (NFPA 99: 2102)	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.	Less than 500 microamps of leakage current at 264 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 264 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1.
Power Supply Fan	N/A	50mm variable speed	70mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
Dimensions	113.5mm x 55mm x 30mm	200mm x 85mm x 53mm	165mm x 95mm x 73mm	90W : 132mm x 57mm x 30mm 120W : 148mm x 75.5mm x 25.4mm

Standard Features and Configurable Components (availability may vary by country)

WEIGHTS & DIMENSIONS

	DM	SFF	MT
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34.2 mm	3.74 x 11.7 x 10.6 in 95 x 296 x 270 mm	6.69 x 10.79 x 13.3 in 170 x 274 x 338 mm
System Volume	64 cu in 1.05 L	463 cu in 7.6 L	960 cu in 15.74 L
System Weight [1]	2.74 lbs 1.25 kg	9.98 lbs 4.54 kg	15.77 lbs 7.14 kg
Max Supported Weight (desktop orientation)	N/A	77 lb 35 kg	77 lb 35 kg
Packaging (W x D x H)	19.57 x 5.04 x 8.78 in 497 x 128 x 223 mm	15.71 x 9.06 x 19.65 in 399 x 230 x 499 mm	15.35 x 11.73 x 19.65 in 390 x 298 x 499 mm
Shipping Weight	6.52 lbs 2.97 kg	16.12 lbs 7.32 kg	22.64 lbs 10.28kg
Shipping Weight (Molded Pulp)	N/A	16.62 lbs 7.54 kg	23.15 lbs 10.50 kg
Palletization Profile	18-units per layer 5 or 6 layers max depending on details of air freight 90 or 108 units per palet depending on details of air freight 45.354 x 39.13 x 57.80 in, 1152 x 994 x 1468 mm (include pallet)	6-units per layer 10 layer max 60 per pallet 47.24 x 39.37 x 95.95 in, 1200 x 1000 x 2438 mm (including pallet)	6-units per layer 7 layer max 42 per pallet 47.24 x 39.37 x 87.79 in, 1200 x 1000 x 2230 mm (including pallet)

1. Configured with 1 HDD & 1 ODD; DM configured with 1 HDD only

Standard Features and Configurable Components (availability may vary by country)

All in One Dimensions

Weight

21.5 Non-Touch Product Weight (Unboxed)	Without Stand: 8.61 ~ 10.36 lbs, 3.91 ~ 4.7 kg Cantilever Stand: 10.93 ~ 12.68 lbs, 4.96 ~ 5.75 lbs Height Adjustable Stand: 12.74 ~ 14.48 lbs, 5.78 ~ 6.57 kg
21.5 Touch Product Weight (Unboxed)	Without Stand: 8.64 ~ 10.19 lbs, 3.92 ~ 4.62 kg Cantilever Stand: 10.96 ~ 12.5 lbs, 4.97 ~ 5.67 kg Height Adjustable Stand: 12.76 ~ 14.31 lbs, 5.79 ~ 6.49 kg
21.5 Shipping Weight (Boxed)	Without Stand: 16.17 ~ 20.0 lbs, 7.34 ~ 9.08 kg Cantilever Stand: 18.85 ~ 22.69 lbs, 8.55 ~ 10.29 kg Height Adjustable Stand: 20.66 ~ 24.67 lbs, 9.37 ~ 11.19 kg
21.5 Shipping Weight (Pallet) - Air Ship Container	Without Stand: 485.2 ~ 605.44 lbs, 220.08 ~ 274.62kg Cantilever Stand: 452.5 ~ 548.69 lbs, 205.25 ~ 248.88 kg Height Adjustable Stand: 495.49 ~ 591.61 lbs, 224.93 ~ 268.56
Dimensions (W x D x H)	
21.5 System Dimensions (including Touch, Non-Touch)	Without Stand: 19.26 x 2.04 x 12.64 in, 489.1 x 51.9 x 321 mm Cantilever Stand: 19.26 x 5.9 x 14.35 in, 489.1 x 149.97 x 364.4 mm Height Adjustable Stand: 19.26 x 8.21 x 14.32 in, 489.1 x 208.47 x 363.69 mm
21.5 Shipping Dimensions (Boxed)	Without Stand: 24.88 x 7.17 x 18.31 in, 632 x 182 x 465 mm Cantilever Stand: 23.46 x 9.69 x 18.43 in, 596 x 246 x 468 mm Height Adjustable Stand: 23.46 x 9.69 x 18.43 in, 596 x 246 x 468 mm
21.5 Shipping Dimensions (Pallet) - Air Ship Container	Without Stand: 47.24 x 39.37 x 60.59 in, 1200 x 1000 x 1539 mm Cantilever Stand: 47.24 x 39.37 x 60.94 in, 1200 x 1000 x 1548 mm Height Adjustable Stand: 47.24 x 39.37 x 60.94 in, 1200 x 1000 x 1548 mm
21.5 Pallet Quantity (including Touch, Non-Touch)	Without Stand: 30 Cantilever Stand: 24 Height Adjustable Stand: 24

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel® Wired for Management support; industry wide initiative to make Intel® architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
  - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
    - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
    - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
    - 2 red + 4 white BIOS recovery is in progress
    - 3 red + 2 white Memory could not be initialized
    - 3 red + 3 white Graphics adaptor could not be found
    - 3 red + 4 white Power supply failure / not connected
    - 3 red + 5 white Processor not installed
    - 3 red + 6 white Current processor does not support an enabled feature
    - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
    - 4 red + 3 white System internal temperature has exceeded its threshold
    - 5 red + 2 white System controller firmware is not valid
    - 5 red + 3 white System controller detected BIOS is not executing
    - 5 red + 4 white BIOS could not complete initialization / PCA failure
    - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:
  - This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software5
- 5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- Clear Password Jumper
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED - To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification

Technical Specifications – Miscellaneous Features

Additional Features

Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only
Drive Protection System	DPS Access through F10 Setup during Boot
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMART IV - End-to-End CRC for hard drives	Detects errors in Read/Write buffers on HDD cache RAM

AFTER MARKET OPTIONS

Graphics Solutions	DM	SFF	MT	AiO	Part Number
AMD Radeon RX 550 4GB 2DP Card			X		3TK71AA
AMD Radeon R7 430 2GB 2DP Card		X	X		3MQ82AA
HP DisplayPort To HDMI True 4k Adapter	X	X	X	X	2JA63AA
HP DVI Cable Kit	X	X	X	X	DC198A
HP HDMI Standard Cable Kit	X	X	X	X	T6F94AA
HP DisplayPort Cable Kit	X	X	X	X	VN567AA
HP DisplayPort To VGA Adapter	X	X	X	X	AS615AA
HP DisplayPort To DVI-D Adapter	X	X	X	X	FH973AA

Desktop Mini Accessories	DM	SFF	MT	AiO	Part Number
HP Desktop Mini G3 Port Cover Kit	X				1ZE52AA
HP G4 Mini 2.5-inch SATA Drive Bay Kit	X				3TK91AA
HP Desktop Mini LockBox V2	X				3EJ57AA
HP Desktop Mini 500GB HDD/I/O Expansion Module	X (Either one)				K9Q82AA
HP Desktop Mini DVD-Writer ODD Expansion Module					K9Q83AA
HP Desktop Mini I/O Expansion Module					K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v2	X				2JA32AA
HP Desktop Mini Vertical Chassis Stand	X				G1K23AA
HP DM VESA Power Supply Holder Kit	X (Must use in conjunction with Dual VESA Sleeve V2)				1RL87AA

Data Storage Drives	DM	SFF	MT	AiO	Part Number
HP 256GB SATA TLC Non-SED Solid State Drive	X	X	X	X	P1N68AA
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	X	X	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X	X	X8U75AA
HP PCIe NVME TLC 512GB SSD PCIe Drive		X	X		Z4L70AA
HP 500GB 7200PRM SATA 6.0Gb/s 3.5" Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 6Gb/s 3.5" Hard Drive		X	X		QK555AA
HP SATA SuperMulti JB Drive			X		QS208AA
HP 9.5mm Slim Removable SATA 500GB		X	X		T7G14AA
HP 9.5mm G3 8/6/4 SFF G4 400 SFF/MT DVD Writer		X			1CA53AA
HP 9.5mm G3 800/600 Tower DVD-Writer			X		1CA52AA

Technical Specifications – After Market Options

Input Devices	DM	SFF	MT	AiO	Part Number
HP USB Grey SmartCard CCID Keyboard (EMEA Only)		X	X		J7H70AA
HP USB Antimicrobial Business Slim Keyboard and Mouse (China Only)		X	X	X	Z9H50AA
HP USB Business Slim CCID SmartCard Keyboard	X	X	X	X	Z9H48AA
HP USB Business Slim (Grey) Keyboard (EMEA Only)	X	X	X	X	Z9H49AA
HP USB Business Slim Keyboard	X	X	X	X	N3R87AA
HP USB Business Slim Keyboard and Mouse and Mousepad		X	X	X	T4E63AA
HP USB Collaboration Keyboard	X	X	X		Z9N38AA
HP USB Conferencing Keyboard				X	K8P74AA
HP USB Keyboard	X	X	X	X	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X	1VD81AA
HP USB Premium Keyboard	X	X	X	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	X	X	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X	N3R88AA
HP Wireless Collaboration Keyboard	X	X	X		Z9N39AA
HP Wireless Premium Keyboard		X	X		Z9N41AA
HP PS/2 Business Slim Keyboard		X	X		N3R86AA
HP USB Grey v2 Mouse (EMEA only)	X	X	X	X	Z9H74AA
HP USB Premium Mouse	X	X	X	X	1JR32AA
HP PS/2 Mouse		X	X		QY775AA
HP USB 1000dpi Laser Mouse	X	X	X	X	QY778AA
HP USB Hardened Mouse	X	X	X	X	P1N77AA
HP USB Mouse	X	X	X	X	QY777AA

Communication Devices	DM	SFF	MT	AiO	Part Number
Intel 9260 802.11ac non-vPro™ PCIe x1 Card		X	X		3TK89AA
Realtek 8822BE 802.11ac PCIe x1 Card		X	X		3TK90AA

System Memory	DM	SFF	MT	AiO	Part Number
HP 4GB DDR4-2666 DIMM		X	X		3TK85AA
HP 8GB DDR4-2666 DIMM		X	X		3TK87AA
HP 16GB DDR4-2666 DIMM		X	X		3TK83AA
HP 4GB DDR4-2666 SODIMM	X			X	3TK86AA
HP 8GB DDR4-2666 SODIMM	X			X	3TK88AA
HP 16GB DDR4-2666 SODIMM	X			X	3TK84AA

Technical Specifications – After Market Options

Multimedia Devices	DM	SFF	MT	AiO	Part Number
HP Business Headset v2	X	X	X	X	T4E61AA
HP USB Business Speakers v2	X	X	X		N3R89AA

Security Devices	DM	SFF	MT	AiO	Part Number
HP Solenoid Lock & Hood Sensor (MT)			X		
HP Business PC Security Lock v3 Kit		X	X		3XJ17AA
HP Dual Head Keyed Cable Lock	X	X	X		T1A64AA
HP Keyed Cable Lock 10mm	X	X	X	X	T1A62AA
HP Master Keyed Cable Lock 10mm	X	X	X	X	T1A63AA

Stands and Accessories	DM	SFF	MT	AiO	Part Number
HP B300 PC Mounting Bracket	X				2DW53AA
HP B500 PC Mounting Bracket	X				2DW52AA
HP Quick Release Kit	X				EM870AA
HP Single Monitor Arm	X			X	BT861AA
HP ProOne 600/400 G4 VESA Plate				X	4CX33AA
HP ProOne G4 Height Adjustable Stand				X	4CX34AA

I/O Devices	DM	SFF	MT	AiO	Part Number
HP DisplayPort Port Flex IO	X	X	X		3TK72AA
HP HDMI Port Flex IO (400/600/800)	X	X	X		3TK74AA
HP Type-C USB 3.1 Gen2 Port Flex IO	X	X	X		3TK78AA
HP VGA Port Flex IO	X	X	X		3TK80AA
HP Serial Port Flex IO	X				3TK76AA
HP Internal Serial Port (400)		X	X		3TK81AA
HP PCIe x1 Parallel Port Card		X	X		N1M40AA
HP 800/600/400 G3 Serial/ PS/2 Adapter		X	X		1VD82AA

Intel Optane Memory	DM	SFF	MT	AiO	Part Number
Intel Optane Memory 16GB (Cache)	X	X	X	X	1WV97AA

Change Log

Date	Version History	Action	Description of Change
June 8, 2018	From v1 to v2	Update	At a glance, Ports, Environmental
June 12, 2018	From v2 to v3	Update	Ports
June 27, 2018	From v3 to v4	Update	HP 9.5mm Slim Removable SATA 500GB removed for AiO and Non internal bay disclaimer also removed from Bays section, disclaimers adjusted / Ports section note rearranged
July 2, 2018	From v4 to v5	Update	Adding PCI slot into the table on page 20 and HP Workwise removed from SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS
July 4, 2018	From v5 to v6	Update	Environmental tab
July 9, 2018	From v6 to v7	Update	Port Deployment for SFF and MT call outs.
July 18, 2018	From v7 to v8	Update	AiO USB port callouts No.3,4 and 5 updated. Footnote No. 29 removed. HP Quick Release Kit added to Stands and Accessories.
July 24, 2018	From v8 to v9	Update	UEFI version updated to V2.6
July 30, 2018	From v9 to v10	Update	USB sentence reduced in the call outs specs and rest of QS Detail fixed to 64-bit in AMD Radeon 530 Graphic Card
August 2, 2018	From v10 to v11	Update	Palletization profile and shipping weight (Molded Pulp) corrected for DM, SFF and MT
August 10, 2018	From v11 to v12	Update	Hp Velocity removed
August 15, 2018	From v12 to v13	Update	TPM 1.2 mention removed from Security section.
August 21, 2018	From v13 to v14	Update	SFF chasis dimensions updated
September 26, 2018	From v14 to v15	Update	Update for call out number 6 and in HP ProOne 600 G4 21.5" All-in-One Business PC (Touch & Non-Touch) Last bullet added in “At a glance” section